

AMENDMENTS TO THE SPECIFICATION

IN THE SPECIFICATION:

On page 1, immediately preceding paragraph [0002], please amend the section heading as follows:

~~Background Art~~ Description of the Related Art

On page 2, immediately preceding paragraph [0003], please amend the section heading as follows:

~~Disclosure of the Invention~~

On pages 3-4, please replace paragraph [0006] with the following paragraph:

[0006]

According to another aspect of the present invention, there is provided a producing method of a semiconductor device, comprising,

using a substrate processing apparatus, comprising:

a processing chamber which provides a space for flowing desired gas and for depositing a desired film on a substrate;

a lamp unit group having at least one lamp unit which is disposed in the processing chamber and which includes a filament for heating the substrate and a lamp tube surrounding the filament;

at least first and second casings which surround the lamp unit, the first casing surrounding the lamp unit and the second casing surrounding the first casing; and

a refrigerant flowing apparatus for flowing cooling medium to a first space formed between the lamp unit and the first casing, and to a second space formed between the first casing and the second casing,

depositing a desired film on the substrate.